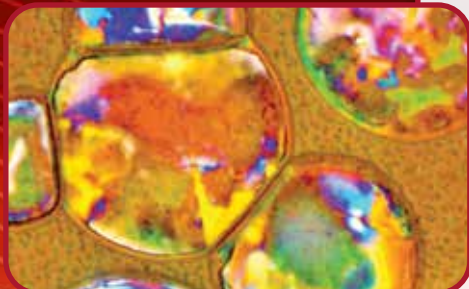


JOM Call for papers

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Low-temperature Technology for Electronic Packaging and Interconnects

This special topic focuses on low-temperature technology for electronic packaging and interconnects.

Original research papers should be 3,000-6,000 words with up to 8 figures maximum; review papers should be 6,000-10,000 words with up to 15 figures maximum.

Detailed author instructions are available at:
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Keywords for this topic: **Electronic Materials; Joining; Molten Metal and Solidification; Phase Transformations; Powder Technology; Low-temperature Materials**

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Committee Sponsor(s): **Electronic Packaging and Interconnection Materials**

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